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(54) COOLER AND SEMICONDUCTOR DEVICE

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(57)**ABSTRACT**

A cooler includes: a cooling wall including a first surface and a second surface; a first path extending in a first direction and having an inlet for a refrigerant; a second path extending in the first direction and having an outlet for the refrigerant; a cooling path causing the first path to communicate with the second path in a second direction intersecting the first direction; a partition spaced from the cooling wall in a third direction perpendicular to the first surface, separating the first and second paths from the cooling paths, and including a third surface constituting a part of a wall surface of the first path, the third surface including a first portion and a second portion differing from the first portion in position in the third direction. The first path includes a first gas retaining space defined by the first and second portions.

